



Business Briefing Functional Products business

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Basic policy and strengths



Aim for co-creation with the customer, and continue to provide solutions

Utilizing the ability to propose and develop new products that meet customer



Lineup of functional products that support 5G and a sustainable society



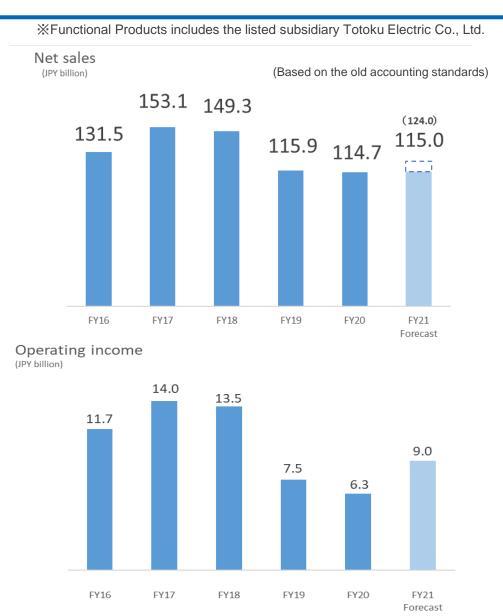
Social issues 9 INDUSTRY, INNOVATION



supplies

Review of the 2020 Medium-term Management Plan





	Topics
FY2016	Increased semiconductor and data center demand (FY2016-FY2017) [AT, Thermal, MD, Copper foil] Higher semiconductor and data center demand provided a tailwind [MD] Continued advancements in customer service with a focus on FUM established in 2015 [Copper foil] Realized the benefits from restructuring operations in Japan
FY2017	[AT] Benefits of developing multiple uses for tape started to appear [Functional plastics] Launched the square EFLEX with the aim of entering the market for eliminating utility poles [Thermal] Data center ranked at the top for the first time in terms of net sales in each market [MD] Thinner products increased, leading to a rapid rise in storage capacity of HDD [Copper foil] Steadily expanded high frequency compatible copper foil and copper foil for batteries
FY2018	Although semiconductor and data center demand steadily increased, demand weakened in H2 due to trade friction and other issues [AT] Memory shipments (monetary basis) peaked in H2 [Functional plastics] Entered the fireproof and waterproof market. Started development of skill-free products [Thermal] Launched the world's first stainless steel vapor chamber [MD] Data center demand rapidly grew and remained strong until the rebound at the end of 2018 [Copper foil] Impacted by the slowing global economy from H2 caused by the trade friction
FY2019	Although data traffic increased, the shortage of processors had a negative impact [AT, Thermal, MD] Lack of processors put the brakes on the businesses [Functional plastics] Increased revenue from duct insulation following the installation of air conditioning in public schools [Copper foil] Significant drop in manufacturing capacity due to the fire at the Taiwan subsidiary, as well as the impact of the large typhoon and other events
FY2020	Supply chain collapsed due to the global COVID-19 pandemic and lockdowns in each country [AT, Thermal, MD] Firm semiconductor and data center demand [Functional plastics] Active renewable energy market in Japan [Thermal] Established an integrated production plant in the Philippines for manufacturing thermal management products for the US [Copper foil] Started restoring manufacturing at the Taiwan subsidiary affected by the fire

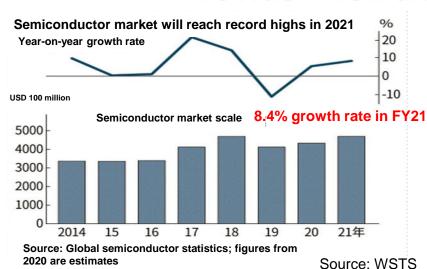
(*Includes the impact of the sale of the listed subsidiary FCM Corporation in December 2018)

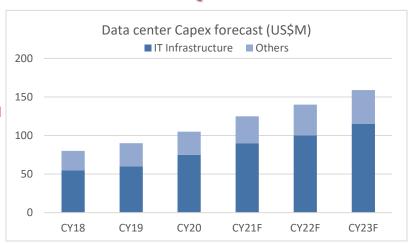
Market overview



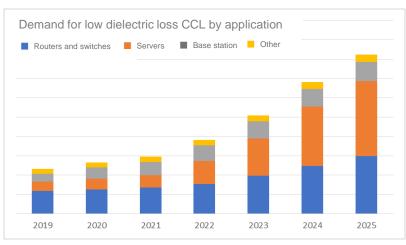


Provide "well-differentiated" products to the trend markets





Source: Omdia





Contribute to further evolution of semiconductors through "heat conduction" and "adhesion" technology



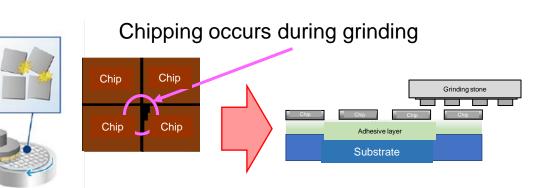
- ✓ As semiconductor chip density increases, heat generation becomes an issue
- ✓ With 3D arrangements resulting from increased data volume, wafers are becoming thinner

Heat resulting from increased chip density

Package gets hot due to heat generated by the chips
Heat
Heat
Heat
Chip
Chip
Chip

Dissipate heat from the semiconductor chip using adhesive film with good thermal conductivity

Chipping due to thinner wafer thickness



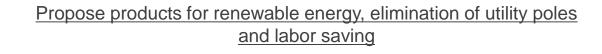
Optimize the conditions by controlling the physical properties of the adhesive and base film

Contribute to increased infrastructure resilience in Japan





Realization of next generation infrastructure



Square EFLEX







Plastic hand hole

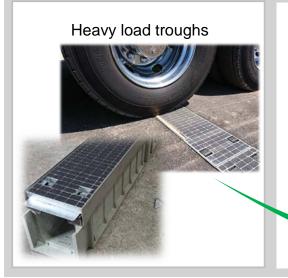


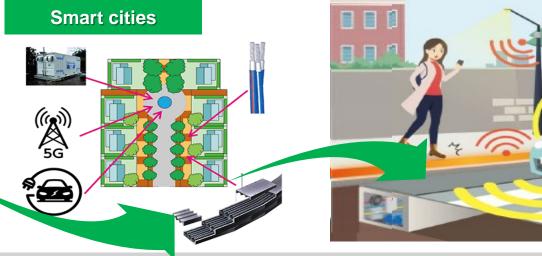
Aqua connector



Expand to
telecommunications
Square DW EFLEX
Conform to overseas
specifications



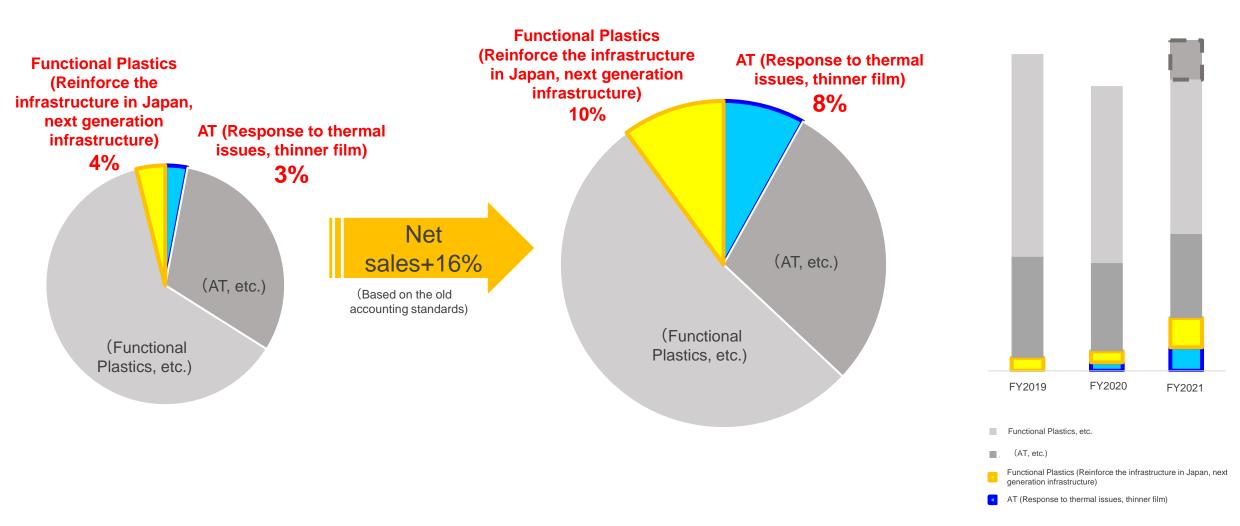




[AT & Functional Plastics] Net sales forecast



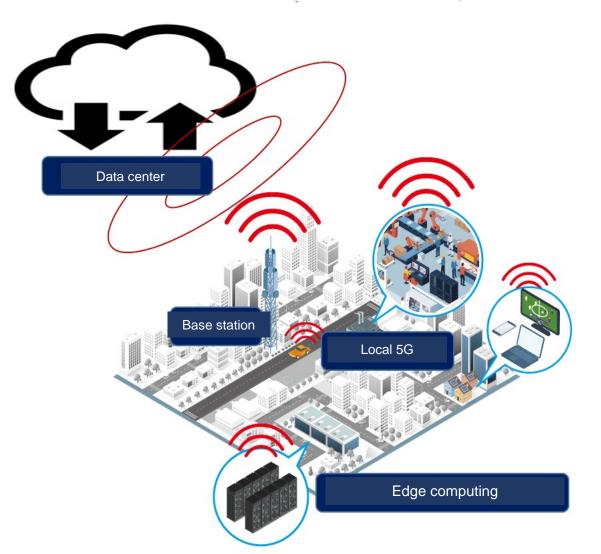
FY2020 FY2021



[Thermal Management Solution & Products] Future outlook



As data traffic increases, the need (quality & quantity) for telecommunications infrastructure (data centers, base stations, etc.) will also increase







Telecommunications infrastructure market (data centers)

More heat generated by CPUs, GPUs, etc.



Provide air conditioning through high performance heat pipes & sinks and 3D vapor chambers

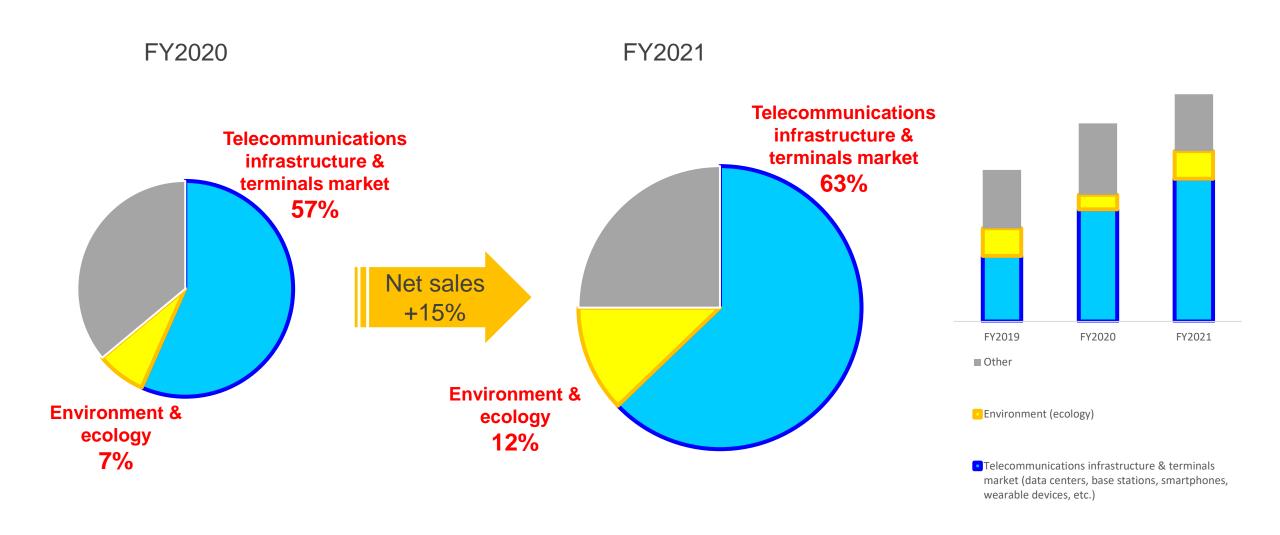
Need for smaller and lighter weight in base stations



Provide one-stop solutions that include the use of heat pipes and large vapor chambers



Telecommunications infrastructure market (base stations)



[Memory Disk] Future outlook

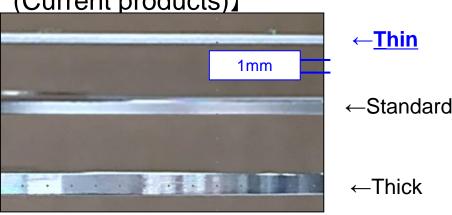


As blanks become thinner, grow by responding to customer needs through well-differentiated materials

Height:
About
2.5cm

Number of disks continues to increase, and there are now HDD with <u>9 disks</u> (Image%: 18TB model with 9 disks)

[Comparison of blank thickness (Current products)]



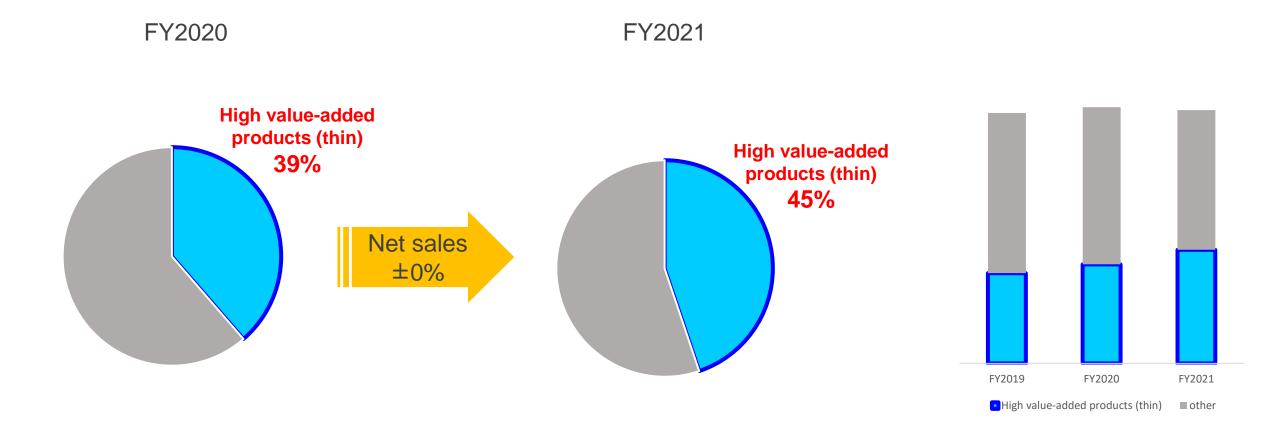
(Thin disks have a thickness of less than 1mm; Images are all Furukawa Electric blanks)

- ✓ As data volume increases, HDD will continue to be equipped with more disks per unit
- ✓ As the number of disks increases, each disk will need to be thinner
- ✓ Respond to the customer need for "thinner disks", and fulfill market expectations by launching

※Image: Excerpt from Western Digital Blog https://blog.westerndigital.com/hdd-magic-20tb-18tb/

well-differentiated new materials





[Copper Foil] Future outlook



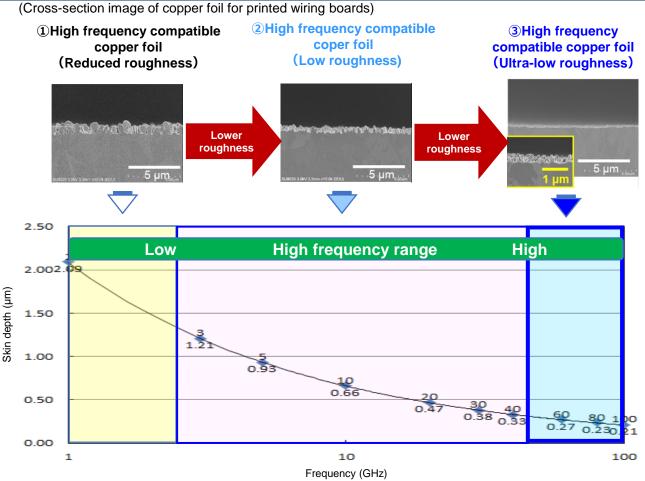
Development and launch of copper foil for high frequency circuit boards that reduces transmission loss

As data traffic increases, transmission by the circuit boards in switches, routers, servers and other devices will need to be in high frequency range

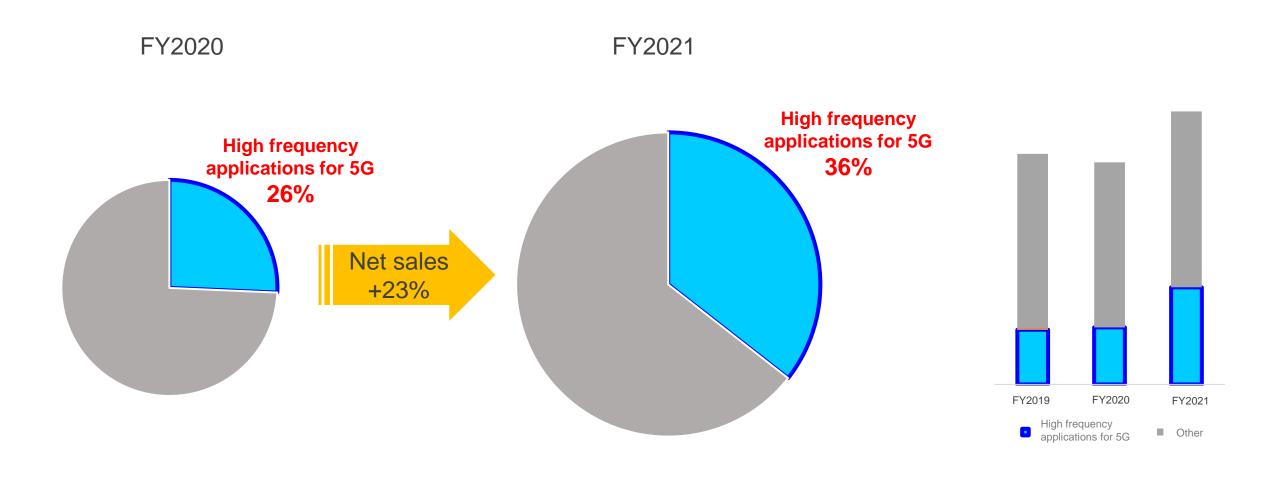


Reduce transmission loss

(Cross-section image of copper foil for printec



✓ Focus on the development and commercialization of next generation high frequency compatible copper foil that achieves both lower transmission loss in the high frequency range and good adhesion to plastic circuit boards by reducing the foil surface roughness



Thank you very much for your attention.



Appendix - Business overview



[FY2021 (Year zero of the 2025 Medium-term Management Plan) basic policy (directed toward achieving Vision 2030)]

By focusing on differentiation, provide well-differentiated products to the growing markets (trend markets)

Entering the era of coexistence with COVID-19, quickly strengthen development and manufacturing
capability to enable flexible responses to the rapidly changing market conditions



(Strengths as a division)

- Strong technology development capability for high performance products
- Rapid, thorough service that combines engineering and sales

[External environment – Main revenue opportunities]

- Growing telecommunications infrastructure demand resulting from increased data traffic and establishment of 5G
- Contribute to the realization of a sustainable society

(Issues and initiatives)

- Maintain and improve the design/ development capabilities for continuing to generate welldifferentiated technology
- Optimize the locations with consideration for the BCP
- Restore the damage caused by the fire at the Taiwan copper foil plant

(External environment – Main risks)

- Changes to the supply chain caused by political factors (including geopolitical risk)
- Disruption to the global economy caused by a natural disaster or new pathogen/ virus

[Future outlook]

- Demand in the telecommunications infrastructure market will continue to expand due to the increasing data traffic and further establishment of 5G. We will quickly respond to the changing customer requirements and continue to develop and provide high performance (well-differentiated) products.
- Through products directed at Society 5.0 for SDGs, we will contribute to the realization of a sustainable society and work to expand the new product domains that will become the foundation of future profits.











Appendix – **Product overview**



	AT* & Functional Plastics *AT : Advanced Technology Tape		Thermal Management Solution & Products	Memory Disk	Copper foil	
Renewable energy		•	•			
Telecommunications infrastructure	•	•	•	•	•	
Disaster prevention and mitigation		•				
Products	Tape for semiconductor process	Cable protective pipes Troughs made from recycled materials Insulation materials	Copper, etc. including heat sinks and heat pipes	Aluminum blanks for HDD	Electrolytic copper foil for printed wiring boards	Electrolytic copper foil for batteries
Applications	Surface protection, immobilizing, etc. during semiconductor wafer processing Semiconductor chip stacking in flash memory	 Protective pipes for underground cable Troughs for holding cables Insulation for air conditioning ducts 	Heat dissipation and cooling of CPUs and power semiconductors, electronics components, high output LED lighting, etc.	HDD for data centers, desktop computers, surveillance cameras, etc.	Wiring boards for communications devices and electronic devices	Cathode material in lithium ion batteries for electric vehicles, smartphones, power tools, etc.
Customers	Semiconductor manufacturers Foundry manufacturers	General construction companies and subcontractors Railroads Highway public corporations and road subcontractors Air conditioning duct manufacturers	 Data center and telecommunications base station operators Smartphone and PC manufacturers Manufacturers of power conditioners for railroads and solar power Lighting equipment manufacturers, etc. 	HDD substrate manufacturers	Wiring board material manufacturers Lithium ion battery manufacturers	

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